

REMARKS

Applicant has cancelled claims 3-4 without prejudice, and amended the written description of the specification and claims 1-2, 5 and 8-10, so as to place the present invention in a formal position and concisely point out the subject matter which Applicant regards as his invention. Additionally, an amended abstract is accompanied with the response. Applicant respectfully submits that the application has been placed in a formal position, and that all pending claims have been standing in an allowable position, for the following reasons:

Drawing Objections

The drawings are objected to under 37 CFR 1.83(a) as they fail to show every feature of the invention specified in claims.

In response, the features that are not shown in the drawings have been deleted from the claims. Additionally, Applicant has amended the specification and claims 1-2, 5 and 9 to accord with the drawings. Said amendments only place the invention in a clear and concise place and are fully supported by the original drawings and the specification. Thus, no new matter is introduced into the instant application. Applicant respectfully submits that the drawings are in a proper position complying with CFR 1.83(a) and that the objections proposed should now be withdrawn.

Claim Objections

Claims 1, 2, 8 and 10 are objected to because of the following informalities:

1. In claims 1, 2 and 10, the term "sign means" is vague and indefinite;
2. In claim 8, after the term "defining", the term "a" is needed but absent;

and

3. In claims 8 and 10, the term "upwardly exposed to an exterior" is vague and indefinite.

According to Examiner' constructive advices, Applicant has amended claims 1, 2, 5 and 8-10 to place them in a proper and formal position. Therefore, the objections proposed should be withdrawn.

Claim Rejections

Claims 1-10 are rejected under 35 U.S.C. 103(a) as being unpatentable over Applicant's Admitted Prior Art (hereinafter, AAPA) as disclosed on pages 1-2 and FIGS. 5 and 6 of the instant application in view of Bailey U.S. Pat. No. 3,784,957 (hereinafter, Bailey)

In response, firstly, Applicant would like to clarify that the shunt of Bailey is used to short circuit all the lead of an electrical device and rapidly applied to a multi-lead DIL (dual-in-line) integrated circuit and removed therefrom. Additionally, the shunt can also sever as a shipping carrier. However, the instant application is directed to a pick up mechanism for picking up socket connectors. It is clearly concluded that Bailey is directed to the art field obviously different from the present application.

Secondly, though one of the corners of the shunt of Bailey is bevelled for indexing, Bailey and AAPA cooperatively fail to prove that there is any suggestion or motivation to reach the present application claimed in pending claims. More specifically, as shown in FIG. 1 of Bailey, the shunt has a symmetrical configuration except for the bevelled corner. During the shunt being loaded into a flat tray, a bottom of the shunt is not needed to be assured to fit with the tray because the bottom of the shunt is symmetrical with the exception of the bevelled

corner. Additionally, Bailey fails to suggest how to make the bottom of the shunt to fit with the tray. Thus, though the bevelled corner of Bailey can be used for indexing, neither AAPA or Bailey shows the desirability of their combination that the bevelled corner of Bailey can be modified to combine with the pick up of AAPA to make retention protrusions of the pick up mechanism of AAPA correctly engage in corresponding notches of the socket connector of AAPA to hold the pick up mechanism on the socket connector.

In brief, the index (7) of Bailey only indicates a chamfer of the shunt (1) which is believed to form a notch for easy assembling/disassembling the rectangular integrated circuit package with regard to the shunt (1). Understandably, via such an index, the operator may easily grasp the integrated circuit package from the shunt (1). Nowhere in Bailey discloses such index (7) is used for anti-mismatching or orientation purpose. It is because the mating between the shunt (7) and the integrated circuit package is not with only one way orientation but with opposite two ways due to symmetrical structure of the shunt (7). Under this situation, it is unobvious or with no motivation for AAPA to adopt the chamfer structure of Bailey for anti-mismatching or orientation purpose with regard to the corresponding socket.

Accordingly, without gleaning the merit of the instant application, one skilled in the art, having Bailey before him or her, would yet not know why the bevelled corner of Bailey could be used to combine with the pick up mechanism of AAPA so as to assure engagingly mating of the retention protrusions of the pick up mechanism of AAPA in the notches of the socket connector of AAPA. That is, the present invention claimed in pending claims is not obvious with respect to Bailey and AAPA.

Furthermore, Applicant has viewed other cited references and concludes that none of them provides the suggestion or motivation to reach the present application claimed in pending claims as clarified above.

However, claim 1, inter alia, recites “indexing means formed on an edge of the plate member in order to shape the plate member asymmetrical relative to a longitudinal and a transverse axis lines, respectively, and assure engagingly mating of the retention means with the receiving means to hold the pick up mechanism on the socket connector”.

Claim 8, inter alia, recites “an orientation mark is on a top side thereof in a vertical direction whereby it is easy for an operator to assure correct engagement of the first engaging devices with the second engaging device respectively, thereby to assemble the pick up mechanism to the socket with correct orientation”.

Claim 10, inter alia, recites “indexing means on a top side thereof to reshape the plate member to be equipped with an orientation function so as to make sure of non-interference between said retention means and said connector during assembling”.

In view of the above, Applicant respectfully submits that independent claims 1, 8 and 10 are defined over all the references and any combination therebetween, and that independent claims 1, 8 and 10 should be allowed.

All pending dependent should be allowed since their independent claims are allowed.

Furthermore, Applicant earnestly informs Examiner of allowance of Taiwanese application on which the foreign priority of the present application is based. The issue number for Taiwanese application is 570383.

Conclusion

For all the above reasons, Applicant asserts that all the pending claims are patentably distinguishable from the prior art. Therefore, Applicant respectfully submits that this application is now in condition for allowance, and that an action to this effect is earnestly requested.

Respectfully submitted,

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